

REMARKS

INTRODUCTION

In accordance with the foregoing, claims 1 and 14 have been amended, and claims 2 and 15 have been canceled, without prejudice or disclaimer. No new matter has been submitted.

Claims 1, 6-8, 10-14, and 16-26 are pending, with claims 1, 6-8, 10-14, and 16-19 being under consideration.

REJECTIONS UNDER 35 USC 102

Claim 1 stands rejected under 35 U.S.C. 102(b) as being anticipated by Komuro et al., U.S. Patent No. 4,873,622, claim 1 stands rejected under 35 U.S.C. 102(e) as being anticipated by Patil et al., U.S. Patent No. 6,425,655, and claim 1 stands rejected under 35 U.S.C. 102(e) as being anticipated by Akhavain et al., U.S. Patent No. 6,543,880.

It is respectfully submitted that the relied upon references fail to disclose the claimed hot pressure welding.

In addition, it is further respectfully submitted that the relied upon references fail to disclose "wherein the FPC includes a protection layer, protecting the conductor, having an opening through which the bonding portions are exposed is provided in the protection layer, and wherein the opening creates a notch, between the protection layer and the bonding portions of the conductor, particularly for permitting the hot pressure welding of the connector and the bonding portions."

Accordingly, withdrawal of this rejection is respectfully requested.

REJECTIONS UNDER 35 USC 103

Claims 6-8, 10-14, and 16-19 stand rejected under 35 U.S.C. 103(a) as being obvious over Patil et al., in view of Asano, U.S. Patent No. 6,396,665. This rejection is respectfully traversed.

As noted above, independent claims 1 and 14 have been amended to claim both an opening through which the bonding portions are exposed in the protection layer, and "wherein the opening creates a notch, between the protection layer and the bonding portions of the conductor, particularly for permitting the hot pressure welding of the connector and the bonding portions," as recited in claim 1 as only an example.

It is respectfully submitted that neither Patil et al., nor Asano, alone or in combination,

EXHIBIT Y

Prosecution History Table for Lemelson Patents

PATENTS AT ISSUE IN SYMBOLS LAWSUIT (*)

	FILED	RELATION	PATENT	ISSUED
1.	02/16/1979	D of II below	4,338,626	07/06/1982
2.	07/02/1982	D of 1	4,511,918	04/16/1985
3.	09/15/1986	C of III below	4,984,073	01/08/1991
4.	09/22/1989	C of 3	4,969,038	11/06/1990
5.	12/20/1989	C of 4	5,128,753	07/07/1992
6.	12/20/1989	C of 3	5,119,190	06/02/1992
7.	03/27/1990	C of 3	4,979,029	12/18/1990
8.	03/27/1990	C of 3	5,067,012	11/19/1991
9.	08/22/1990	C of 8	5,023,714	06/11/1991
10.	11/05/1990	C of 3	5,119,205	06/02/1992
11.	01/28/1992	C of 6	5,249,049	09/28/1993
12.	04/23/1992	C of 5	5,144,421	09/01/1992
13.	06/16/1993	C of 10	5,283,641	02/01/1994
14.	09/16/1993	C of 12	5,351,078	09/27/1994

RELATED PATENTS '72 SPEC (Common Specification for Family At Issue)

	FILED	RELATION	PATENT	ISSUED
I.	05/18/1972	(CIP of C Below)	4,118,730	11/03/1978
II.	03/16/1977	C of I. (4,118,730)	4,148,061	04/31/1979
III.	04/15/1985 (**)	C of 2 above	4,660,086	04/21/1987

Parent CIP Applications

	FILED	RELATION	PATENT	ISSUED
A	12/24/1954 (***)	Parent	App. No. (05/?) 477,467	Abandoned
B	12/04/1956	CIP of A	3,081,379 [App. No. (05/?) 626,211]	3/12/63
C	03/11/1963 (****)	CIP of B or A and B	App. No. (05/?) 267,377	Abandoned

(*) Federal Circuit noted, in Sept. 2005 Decision, that Lemelson asserted that 68 of 76 asserted claims were entitled to priority from 1963 application (C above), so at least 8 claims at suit solely derived support from '72 spec.

(**) District Court, in January 23, 2004 Decision, indicated that by the year of issuance of this patent all claims originally filed with the 1972 application (I. above; common specification) had issued in a patent.

(***) District Court, in January 23, 2004 Decision, indicated that successor to this application issued in 1969, on page 5, and in 1962 on page 9.

(****) District Court, in January 23, 2004 Decision, determined that the 1963 application did not have sufficient relationship to '54 and '56 applications to be CIP application.

disclose or suggest the particularly claimed notch particularly for permitting the claimed hot pressure welding.

Rather, as noted previously, it is respectfully submitted that the present invention has a particular orientation of the connector, and particularly explains how the connector can connect to each of the pad or bonding portions. **In particular, the notch implemented by the present invention created by the claimed opening permits the use of the claimed hot pressure welding.**

Thus, it is respectfully submitted that it would not have been obvious to modify Patil et al. to disclose the presently claimed invention.

Therefore, for at least the above, it is respectfully requested that the outstanding rejections be withdrawn and the presently claimed invention be allowed.

CONCLUSION

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

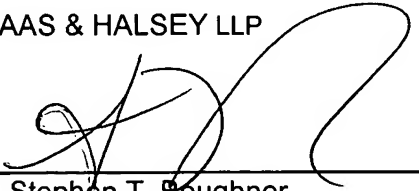
Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

STAAS & HALSEY LLP

Date: 12/30/05

By: 
Stephen T. Boughner
Registration No. 45,317

1201 New York Avenue, NW, Suite 700
Washington, D.C. 20005
Telephone: (202) 434-1500
Facsimile: (202) 434-1501